

1. Part No. Expression:

P D B 1 6 0 8 1 R 0 M Z F

(a) (b) (c) (d) (e)(f)

(a) Series Code

(b) Dimension Code

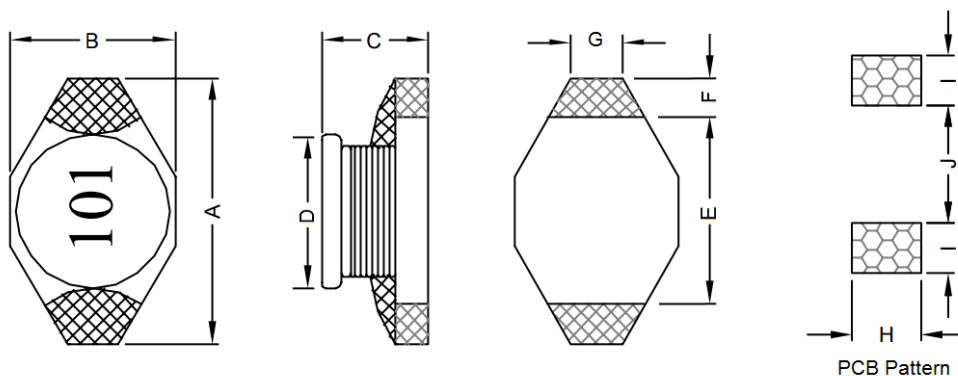
(c) Inductance Code

(d) Tolerance Code

(e) Standard Part Code

(f) RoHS Compliant

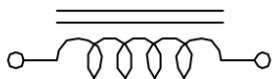
2. Configuration & Dimensions



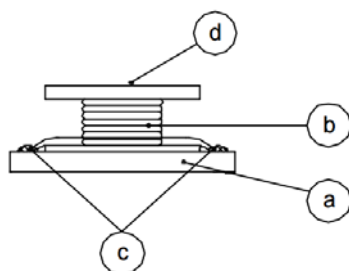
Unit: mm

A	B	C	D	E	F	G	H	I	J
6.60 Max.	4.45 Max.	2.92 Max.	3.94 Typ.	4.32 Typ.	1.02 Typ.	1.27 Typ.	3.56	1.40	4.06

3. Schematic



4. Material List



(a) Base

(b) Wire

(c) Epoxy

(d) Marking

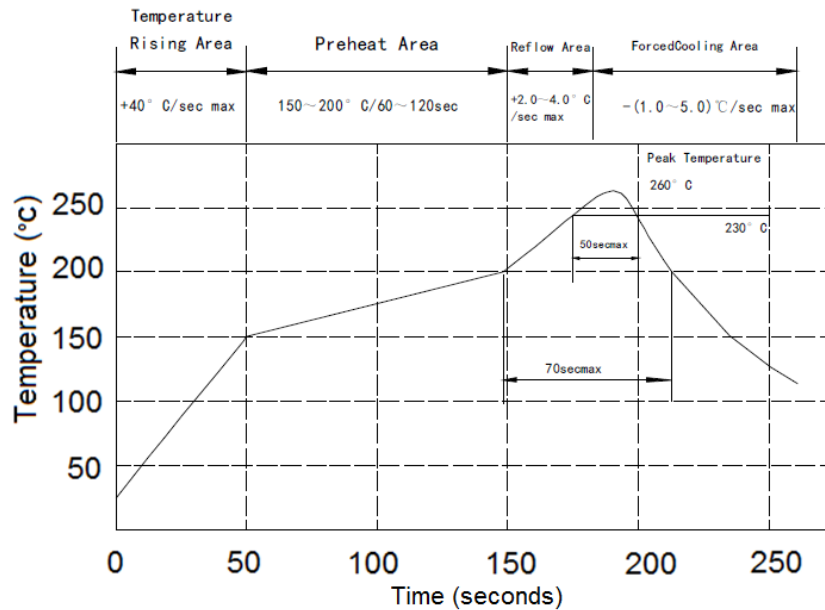
5. General Specification

- (a) Temperature rise: 40°C Max. at Irms
- (b) Rated current : $\Delta L/L_0A$: 10% Max. at Isat
- (c) Operating Temp. : -40°C to +85°C
- (d) Storage Temp. : -40°C to +125°C (on board)
- (e) Storage Condition (Component in its packaging)
 - i) Temperature: Less than 40°C
 - ii) Humidity : 70% RH

6. Electrical Characteristics

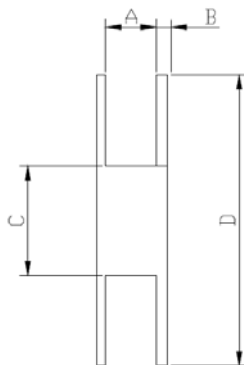
Part Number	Inductance (uH)	Test Frequency (Hz)	SRF (MHz) Typ.	DCR (Ω) Max.	Irms (A)	Isat (A)
PDB16081R0MZF	1.0 $\pm$ 20%	0.1V/100K	130.0	0.05	2.90	2.90
PDB16081R5MZF	1.5 $\pm$ 20%	0.1V/100K	115.0	0.06	2.80	2.60
PDB16082R2MZF	2.2 $\pm$ 20%	0.1V/100K	90.0	0.07	2.40	2.30
PDB16083R3MZF	3.3 $\pm$ 20%	0.1V/100K	70.0	0.08	2.00	2.00
PDB16084R7MZF	4.7 $\pm$ 20%	0.1V/100K	50.0	0.09	1.50	1.50
PDB16086R8MZF	6.8 $\pm$ 20%	0.1V/100K	45.0	0.13	1.40	1.20
PDB1608100MZF	10.0 $\pm$ 20%	0.1V/100K	35.0	0.16	1.10	1.10
PDB1608150MZF	15.0 $\pm$ 20%	0.1V/100K	30.0	0.23	1.00	0.90
PDB1608220MZF	22.0 $\pm$ 20%	0.1V/100K	20.0	0.37	0.80	0.70
PDB1608330MZF	33.0 $\pm$ 20%	0.1V/100K	15.0	0.51	0.60	0.58
PDB1608470MZF	47.0 $\pm$ 20%	0.1V/100K	14.0	0.64	0.50	0.50
PDB1608680MZF	68.0 $\pm$ 20%	0.1V/100K	11.0	0.86	0.40	0.40
PDB1608101MZF	100.0 $\pm$ 20%	0.1V/100K	9.0	1.27	0.30	0.31
PDB1608151MZF	150.0 $\pm$ 20%	0.1V/100K	6.0	2.00	0.25	0.27
PDB1608221MZF	220.0 $\pm$ 20%	0.1V/100K	5.5	3.11	0.20	0.22
PDB1608331MZF	330.0 $\pm$ 20%	0.1V/100K	5.0	3.80	0.16	0.18
PDB1608471MZF	470.0 $\pm$ 20%	0.1V/100K	4.0	5.06	0.15	0.16
PDB1608681MZF	680.0 $\pm$ 20%	0.1V/100K	3.0	9.20	0.12	0.14
PDB1608102MZF	1000.0 $\pm$ 20%	0.1V/100K	2.0	13.80	0.07	0.10

7. Soldering Profile



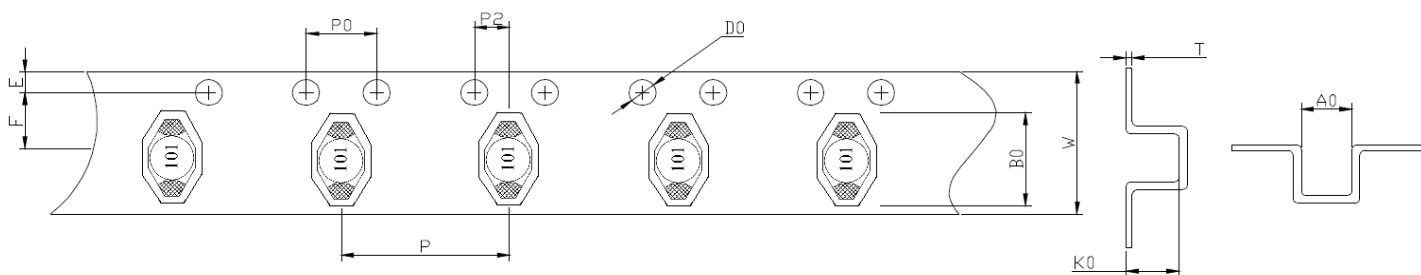
8. Packaging Information:

9-1 Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
13"x16mm	16.5	2.3	100.0	330.0

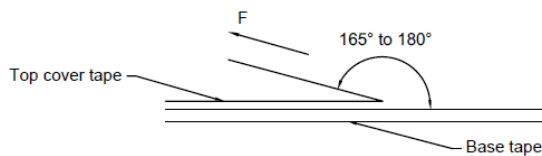
9-2 Tape Dimension



W(mm)	E(mm)	F(mm)	P(mm)	P0(mm)	P2(mm)	D0(mm)	T(mm)	A0(mm)	B0(mm)	K0(mm)
16.00±0.30	1.75±0.10	7.50±0.10	8.00±0.10	4.00±0.10	2.00±0.10	1.50±0.10	0.35±0.05	4.55±0.10	6.90±0.10	3.20±0.10

9-3 Packaging Quantity

Chip Size	PDB1608
Chip/Reel	2,000
Inner Box	6,000
Outer Box	12,000

9-4 Tearing Off Force

The force for tearing off cover tape is 5 to 120 grams in the arrow direction under the following conditions.

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

Application Notice:**1. Storage Conditions:**

To maintain the solderability of terminal electrodes:

- a) Recommended products should be used within 6 months from the time of delivery.
- b) The packaging material should be kept where no chlorine or sulfur exists in the air.

2. Transportation:

- a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- b) Vacuum pick up is strongly recommended for individual components.
- c) Bulk handling should ensure that abrasion and mechanical shock are minimized.